Call for Titles & Abstracts

Titles due: May 19, 2006 Abstracts due June 23, 2006

IEEE-CPMT • iNEMI • Georgia Tech Packaging Research Center (PRC) Sponsor the

Second International Workshop on SOP • SIP • SOC (3S) Electronics Technologies

September 28 & 29, 2006

Global Learning & Conference Center at Technology Square
84 Fifth Street, Atlanta, GA USA

General Chair: Rao R. Tummala, PRC Director
Technical Chair: Dr. Mahadevan Iyer, PRC Research Director
Program Coordinator: Boyd Wiedenman, PRC

Visit our **Web Page** for the full **Call for Papers**

www.prc.gatech.edu/3s

Topics

Mixed signal design and design tools
Embedded RF integration and modules
Mixed signal test
Embedded LTC, organic laminate and Si wafer technologies
Applications and products in automotive, computing, consumer and wireless
Embedded digital integration and modules
Multifunction integration and modules
Mixed signal reliability
Embedded optical integration and modules
Materials, processes, fabrication and assembly
Stacked ICs and packages
Manufacturing

Please send to boyd.wiedenman@ece.gatech.edu

The 8th EMAP conference will be held at Hong Kong University of Science and Technology (HKUST), Hong Kong, **December 11–14, 2006**. The previous seven were held in Singapore (1999), Hong Kong (2000), Korea (2001), Taiwan (2002), Singapore (2003), Malaysia (2004) and Japan (2005).

The EMAP conference will include all fundamental and applied science and technology related to the fields of electronic materials, devices, and packaging. Topics may include, but are not limited to, the following areas:

* Materials and Processing
* Passive and Active Components
* Optoelectronics / Photonics
* Advanced Packaging
* Emerging Packaging Technologies
* Interconnection Technologies
* System-in-Package (SiP) and 3D Stacked Die Packaging
* Electrical Modeling, Characterization, and Signal Integrity
* Thermal-Mechanical Modeling and Characterization
* Packaging Technologies for High Brightness LEDs
* Sensor, Actuator, and Transducer Technologies
* Quality and Reliability

Kindly submit your abstract by June 30, 2006

For more details, and the full Call for Papers, visit **www.ust.hk/emap2006**

Coordinate international travel plans to attend one or two other CPMT Society events: **EPTC'06**, 6-8 December, 2006, in Singapore; and **VLSI Chip Packaging Workshop**, Dec. 4 - 5, 2006, Kyoto, Japan.